

# CTB: Component Technology Board & its EEE Roadmap

Jean-Louis Cazaux, chairman (03/2021)



#### CTB: Component Technology Board

- An ESCC body, subordinate to the SCSB (Space Components Steering Board), along with PSWG (Policy & Standard Working Group) and MPTB (Materials & Processes Technology Board)
- Created in 2002 according to ESCC Charter 00000, Defined by ESCC 10400

The CTB is charged with the formulation of strategic programmes and work plans for technology research and development in the area of European EEE space components.

It **harmonises** the collectively funded component research, development, evaluation, qualification, standardisation and quality assurance activities.



# CTB Membership:

1) Space Agencies:











2) Equipement Manufacturers: through













3) Component Suppliers















+ Observers: IMEC (for RTOs)



+ European Commission

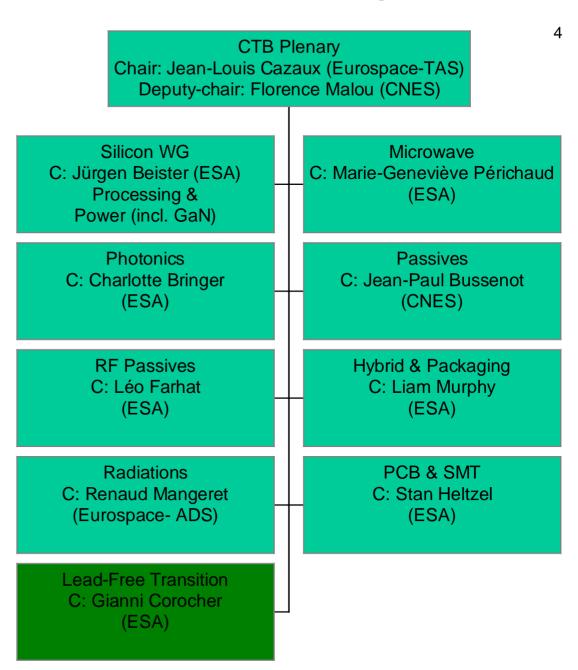




## 8 permanent thematic Working Groups (WG) reporting to the "CTB Plenary"

- In total, and as for today, CTB WGs involve about 200 individuals from 50 different organizations
- + Lead-Free Transition Working Group reporting to CTB and MPTB

#### CTB's Internal Organization



04/03/2021



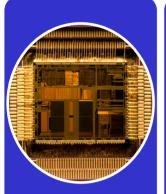
#### The CTB Roadmap:

- Updated continuously
- Released once a year

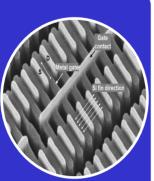
### Presentation which follows is focused on the main axis and priorities, sorted thematically

- Silicon >> computing, processing and power
- Microwave
- Photonics
- Passives and RF passives
- Report and packaging technologies
- Focus on « New Space » mindset with COTS, and Lead-free transition





Consolidation on middlerange technologies: 150nm / 130nm



UDSM for OBDP: under 20nm FDSOI / FinFET 1st activities on 7/6nm

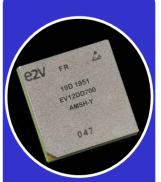


BRAVE FPGA
Family with
NanoXplore:
ULTRA and
ULTRA-300

Simulation tools
Organic
packaging



Microcontrollers
Microprocs
including
RISC-V



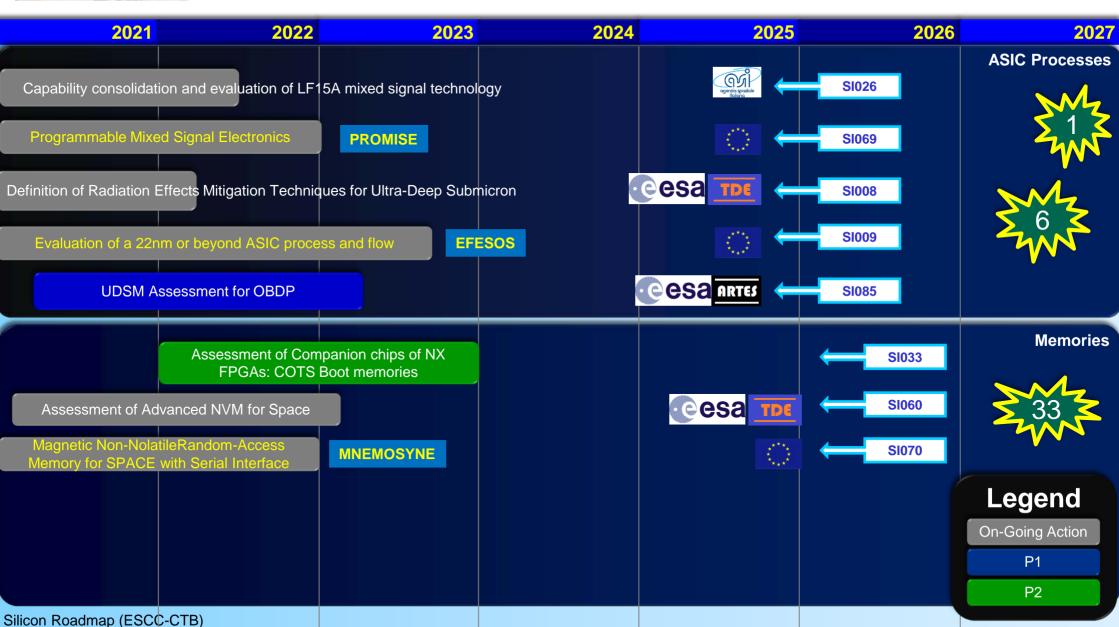
High Speed interface, Ka-Band ADC or Direct Conversion



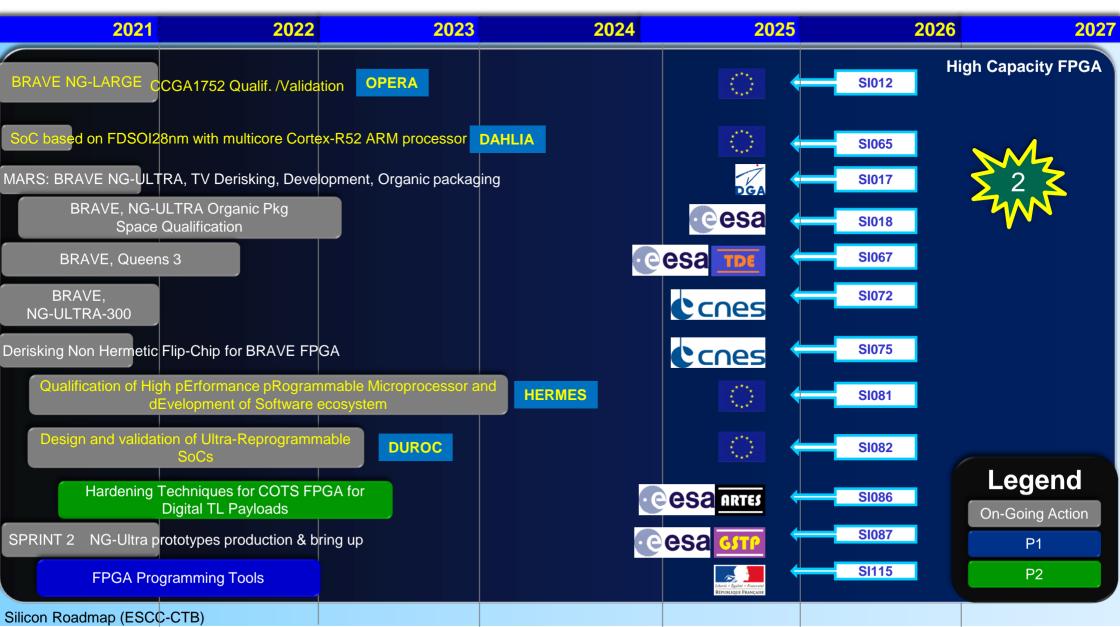
European GaN Power transistors, Power ICs

Silicon (computing, processing, power)

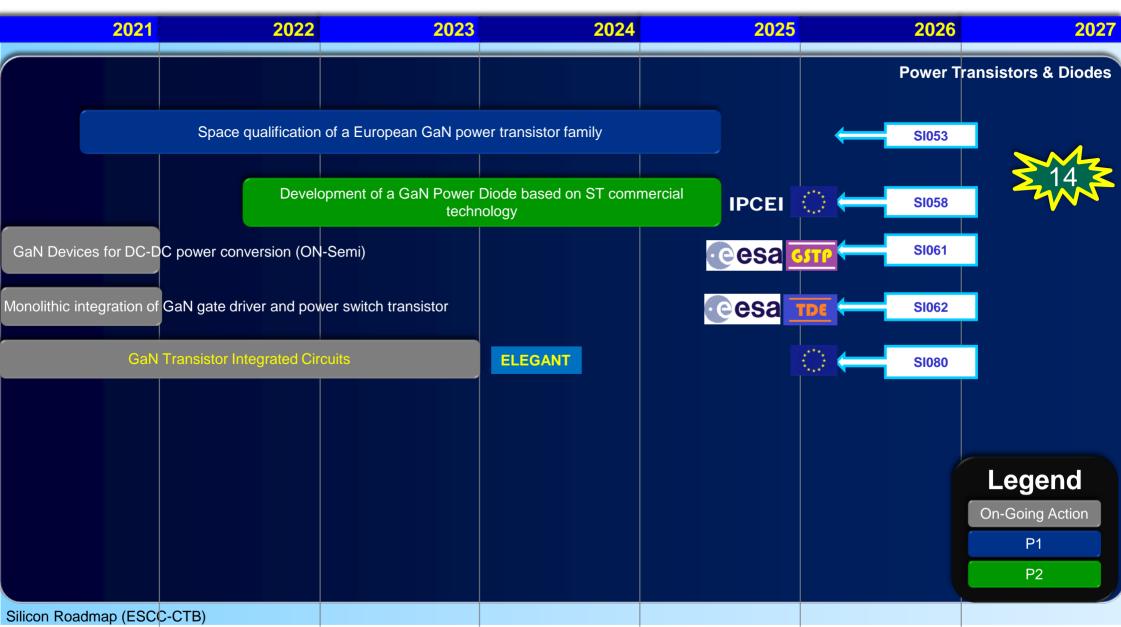








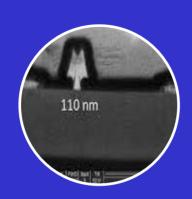




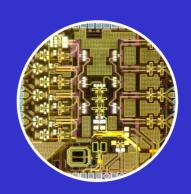




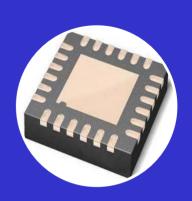
European GaN: Higher power & efficiency in Ku-, Ka-band



European GaN: Higher frequencies, Q/V and beyond



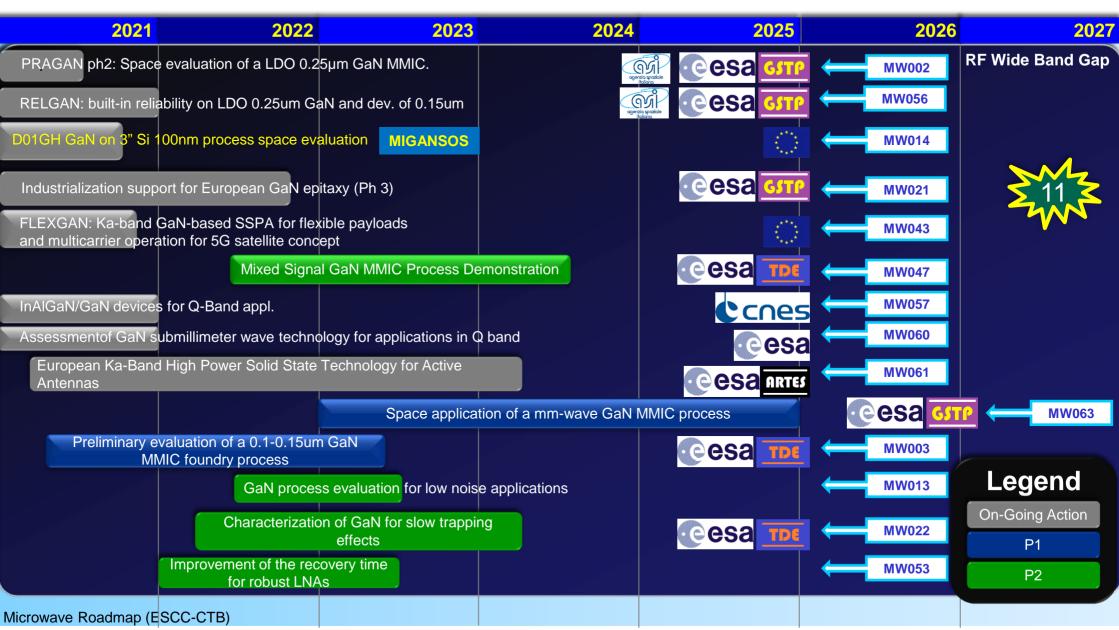
Si-based MMIC: SiGe, RF CMOS



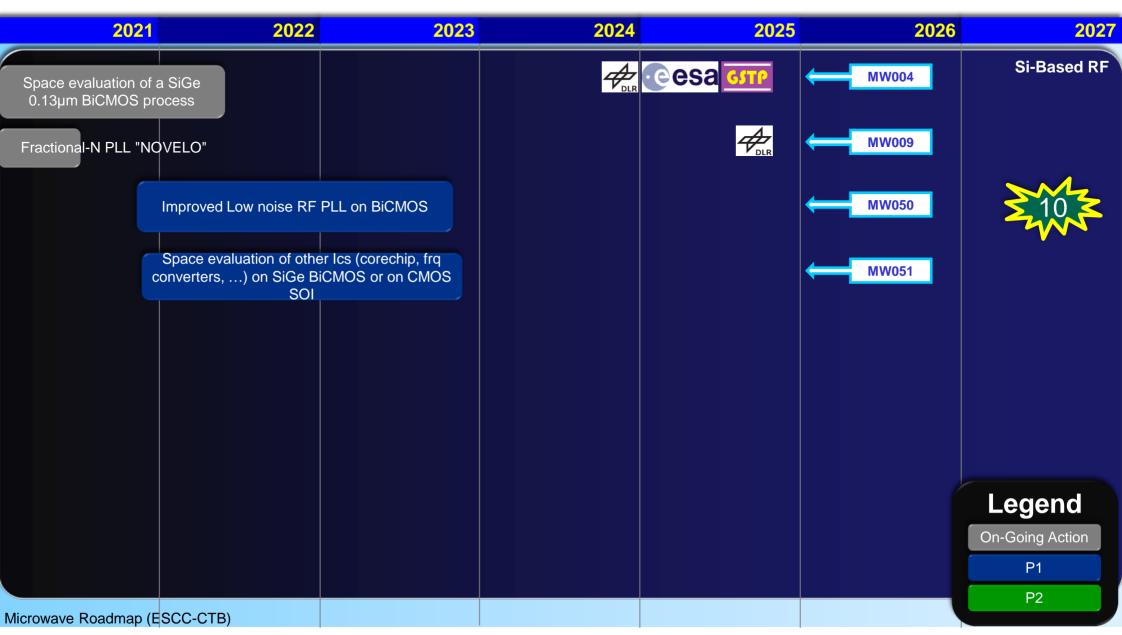
Constraints of non-hermetic packaging

MicroWave













Components for Optical coms, Photonic Payload, Optical digital interfaces Non-dependent, affordable solutions



Photonics Integrated Circuits (PICs)



Optical switch matrices



Passive optical: splitters, connectors, fibers,

. . .

Photonics



#### Passives and RF Passives Priorities

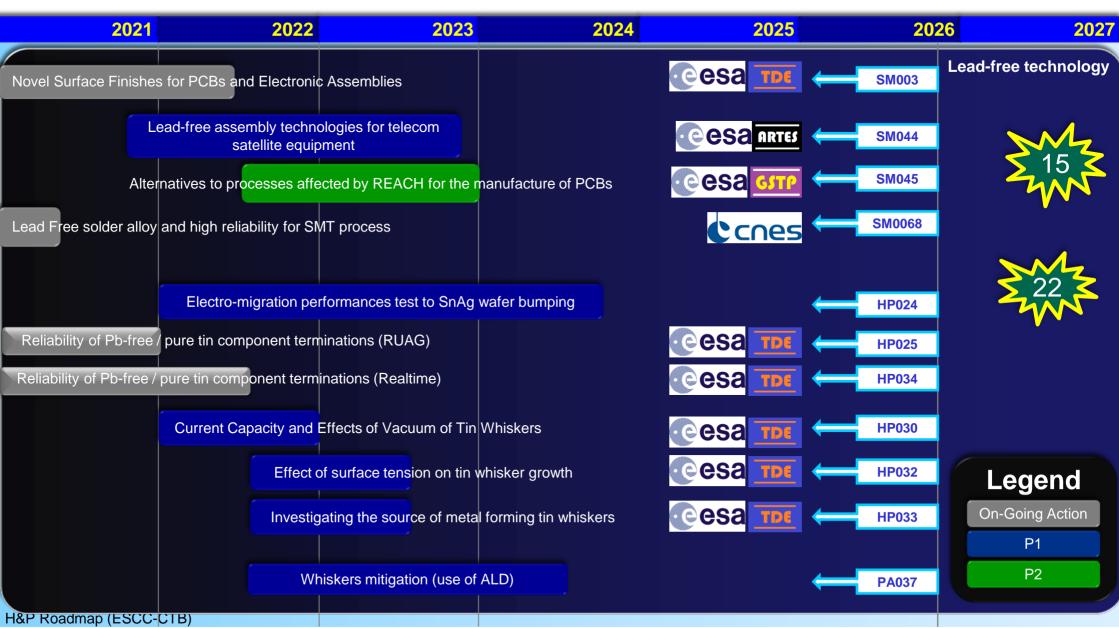




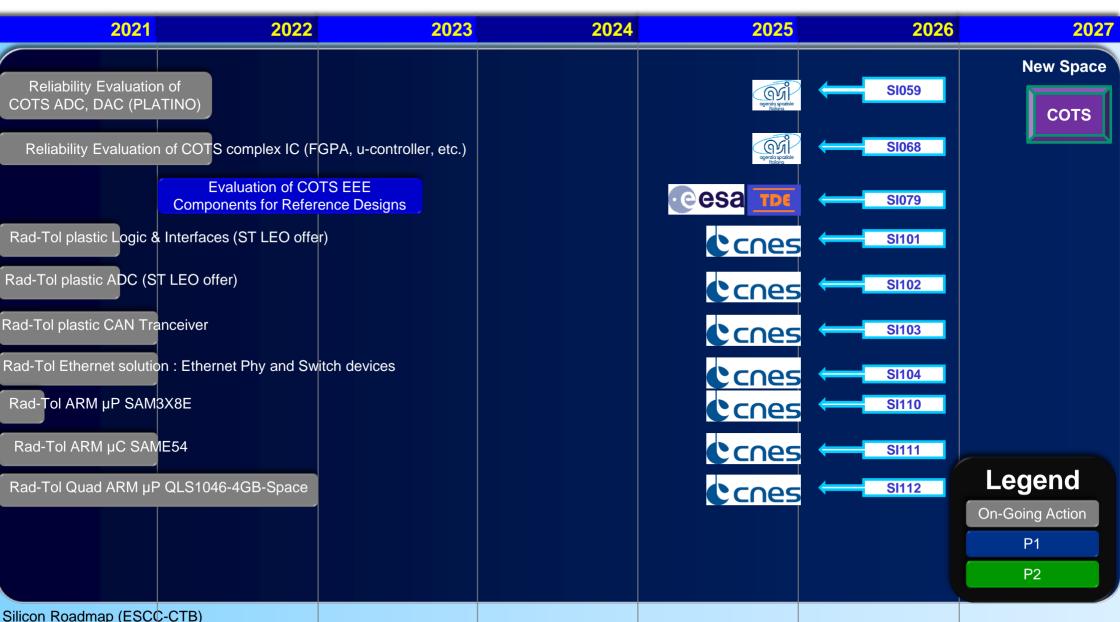
#### Report and Packaging Priorities



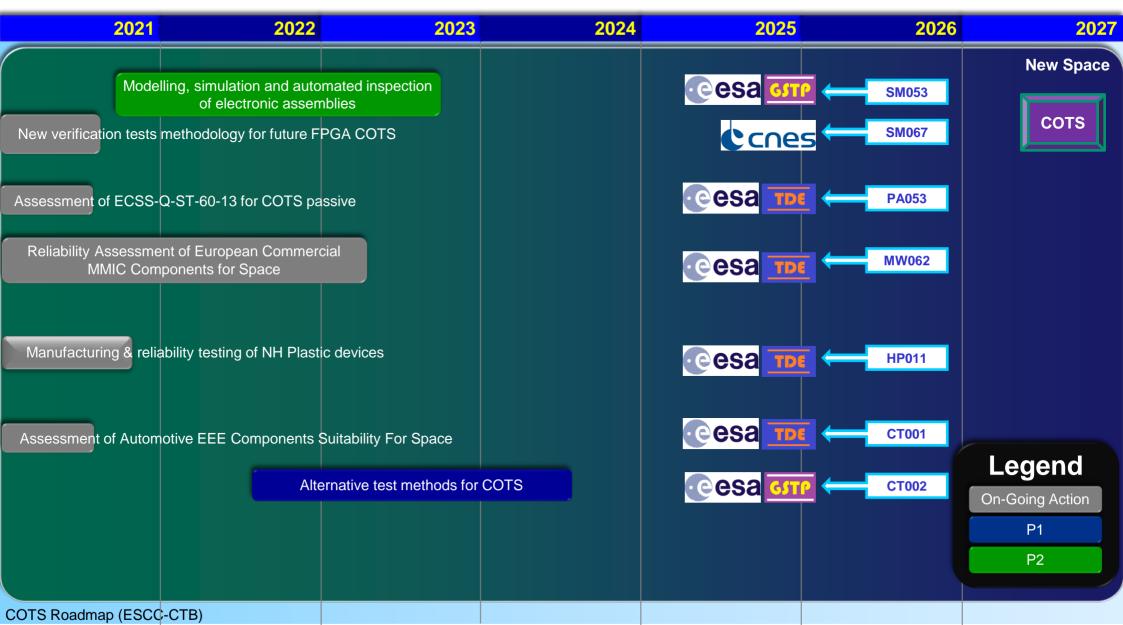








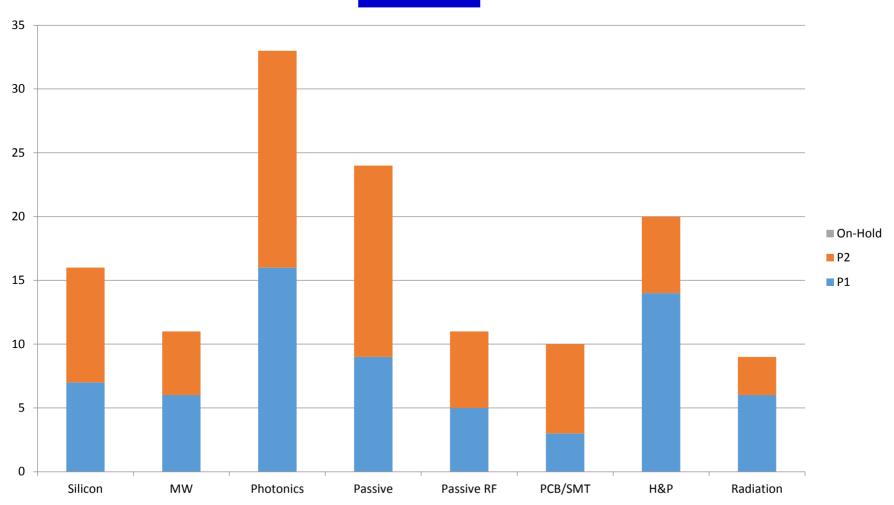






#### Number of activities

P1: 66 P2: 68

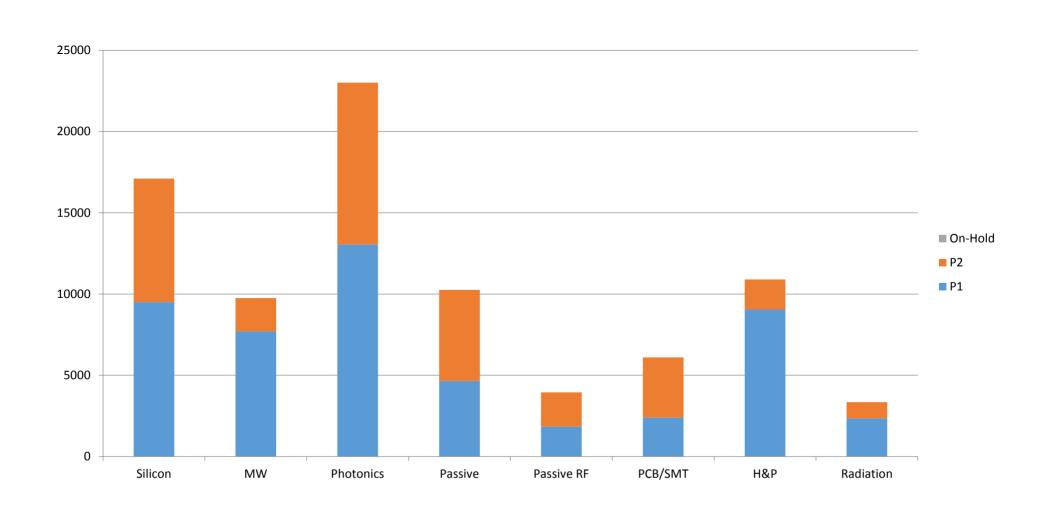








P1: 50 M€/4y P2: 34 M€/4y







# Thank you for your attention

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